

N-Channel 60 V (D-S) MOSFET



PRODUCT SUMMARY				
V _{DS} (V)	60			
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.00385			
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 7.5 \text{ V}$	0.00490			
Q _g typ. (nC)	22			
I _D (A)	92.4			
Configuration	Single			

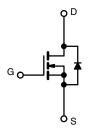
FEATURES

- TrenchFET® Gen IV power MOSFET
- Very low R_{DS} Q_g figure-of-merit (FOM)
- \bullet Tuned for the lowest R_{DS} Q_{oss} FOM
- 100 % R_a and UIS tested
- · Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

COMPLIANT HALOGEN **FREE**

APPLICATIONS

- · Synchronous rectification
- · Primary side switch
- DC/DC converter
- · Motor drive switch



N-Channel MOSFET

ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and halogen-free	SiJ188DP-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V_{DS}	60	V	
Gate-source voltage		V_{GS}	± 20	V	
Continuous drain current (T _J = 150 °C)	T _C = 25 °C		92.4		
	T _C = 70 °C	1 .	73.9		
	T _A = 25 °C	l _D	25.5 ^{b, c}		
	T _A = 70 °C	1	20.3 ^{b, c}	^	
Pulsed drain current (t = 100 μs)		I _{DM}	150	Α	
Continuous source-drain diode current	T _C = 25 °C		59.7		
	T _A = 25 °C	IS	4.5 b, c		
Single pulse avalanche current	1 0.1 ml l	I _{AS}	25		
Single pulse avalanche energy	L = 0.1 mH	E _{AS}	31.25	mJ	
Maximum power dissipation	T _C = 25 °C		65.7		
	T _C = 70 °C	P _D	42	14/	
	T _A = 25 °C		5 b, c	W	
	T _A = 70 °C		3.2 b, c		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	00	
Soldering recommendations (peak temperature) c			260	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient ^b	t ≤ 10 s	R _{thJA}	20	25	°C/W	
Maximum junction-to-case (drain)	Steady state	R _{thJC}	1.6	1.9	7 ·C/W	

- Package limited
- Surface mounted on 1" x 1" FR4 board

S18-0822-Rev. A, 13-Aug-2018

- See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection

 Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

 Maximum under steady state conditions is 70 °C/W

 T_C = 25 °C



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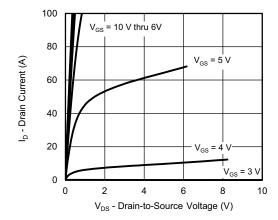
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static					•		
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = 10 mA	-	34	-	1/0	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-6.7	-	mV/°(
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2	-	3.6	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	100	nA	
		V _{DS} = 60 V, V _{GS} = 0 V	-	-	1	μA	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V, T _J = 70 °C	-	-	15		
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	40	-	-	Α	
Delice and a state and a second	D .	$V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	-	0.00320	0.00385	Ω	
Drain-source on-state resistance ^a	R _{DS(on)}	$V_{GS} = 7.5 \text{ V}, I_D = 10 \text{ A}$	-	0.00380	0.00490		
Forward transconductance a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_D = 10 \text{ A}$	-	41	-	S	
Dynamic ^b					•		
Input capacitance	C _{iss}		-	1920	-	pF	
Output capacitance	C _{oss}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	530	-		
Reverse transfer capacitance	C _{rss}	30 1 30 1	-	26	-		
		$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$ $V_{DS} = 30 \text{ V}, V_{GS} = 7.5 \text{ V}, I_D = 10 \text{ A}$	-	29	44		
Total gate charge	Qg		-	22	33	nC	
Gate-source charge	Q _{qs}		-	6.8	-		
Gate-drain charge	Q _{gd}		-	5	-		
Output charge	Q _{oss}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	-	32.5	-		
Gate resistance	R_g	f = 1 MHz	0.3	0.9	1.5	Ω	
Turn-on delay time	t _{d(on)}		-	13	26		
Rise time	t _r	$V_{DD} = 30 \text{ V}, \text{ R}_L = 3 \Omega, \text{ I}_D \cong 10 \text{ A},$	-	6	12		
Turn-off delay time	t _{d(off)}	$V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	22	44		
Fall time	t _f		-	6	12		
Turn-on delay time	t _{d(on)}		-	16	32	ns	
Rise time	t _r	V_{DD} = 30 V, R_L = 3 Ω , I_D \cong 10 A, V_{GEN} = 7.5 V, R_g = 1 Ω	-	8	16	<u> </u>	
Turn-off delay time	t _{d(off)}		-	20	40		
Fall time	t _f		-	8	16		
Drain-Source Body Diode Characteristi	cs		<u>'</u>		•	L	
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	59.7		
Pulse diode forward current	I _{SM}		-	-	150	A	
Body diode voltage	V _{SD}	$I_{S} = 5 \text{ A}, V_{GS} = 0 \text{ V}$	-	0.76	1.1	V	
Body diode reverse recovery time	t _{rr}		-	46	92	ns	
Body diode reverse recovery charge	Q _{rr}	$I_F = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	44	88	nC	
Reverse recovery fall time	ta	$T_{\rm J} = 25 ^{\circ}{\rm C}$	-	21	-		
Reverse recovery rise time	t _b		_	25	<u> </u>	ns	

Notes

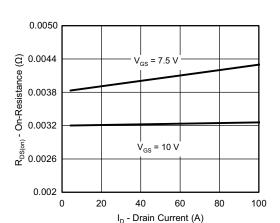
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

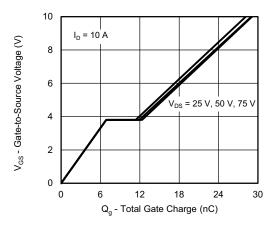




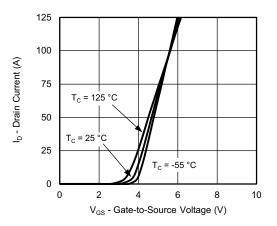
Output Characteristics



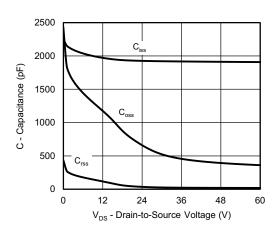
On-Resistance vs. Drain Current and Gate Voltage



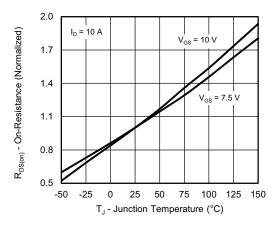
Gate Charge



Transfer Characteristics

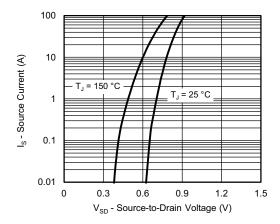


Capacitance

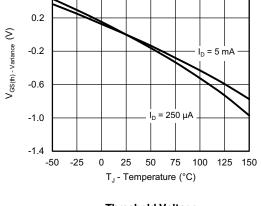


On-Resistance vs. Junction Temperature



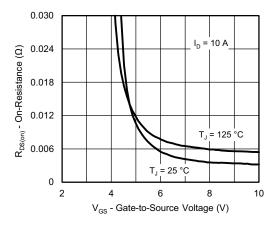


Source-Drain Diode Forward Voltage

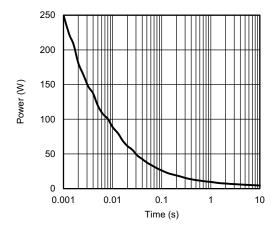


0.6

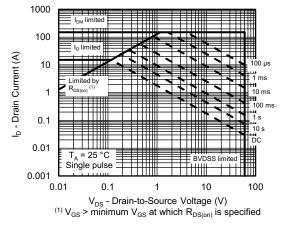
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage

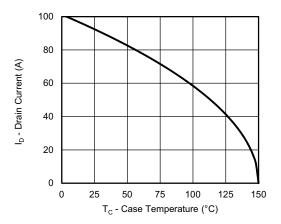


Single Pulse Power, Junction-to-Ambient

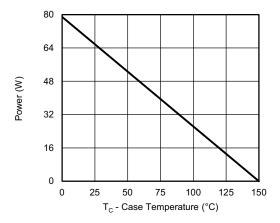


Safe Operating Area, Junction-to-Ambient

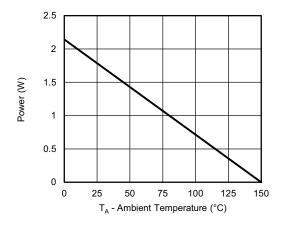




Current Derating a





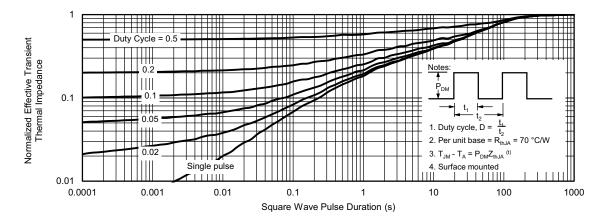


Power, Junction-to-Ambient

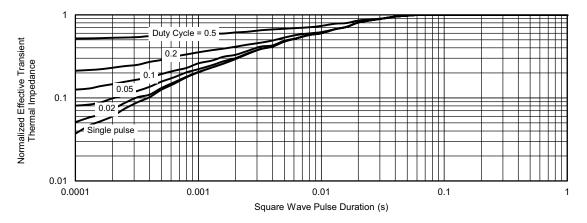
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient

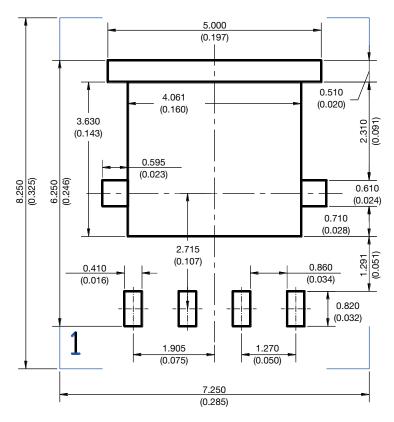


Normalized Thermal Transient Impedance, Junction-to-Case

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RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)



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